

Evaluating Solar Panel Mechanical Durability of Commercial Modules

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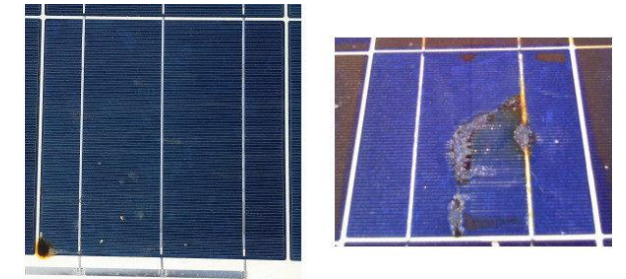


Outline

- **Motivation:** Impact of Cell Cracks and their Origin
- **Methodology:** Typical Mechanical Evaluation Approaches
- **Experimental Results:** Case Study of Commercial Modules
- **Discussion / Conclusions**

Module Mechanical Durability

- PV modules experience a wide range of mechanical stressors over their lifetime that may cause cell cracking
 - shipping, installation, snow, wind, thermal cycling
- Cell cracks pose a risk to long term performance
 - Increase in **series resistance**
 - Increase in “dead area” leading to **current mismatch**
 - Potential for **hot spot** generation
 - Severe hot spots are a potential **safety hazard**
- In this work, a modified mechanical durability test sequence is investigated to evaluate module design with respect to crack durability

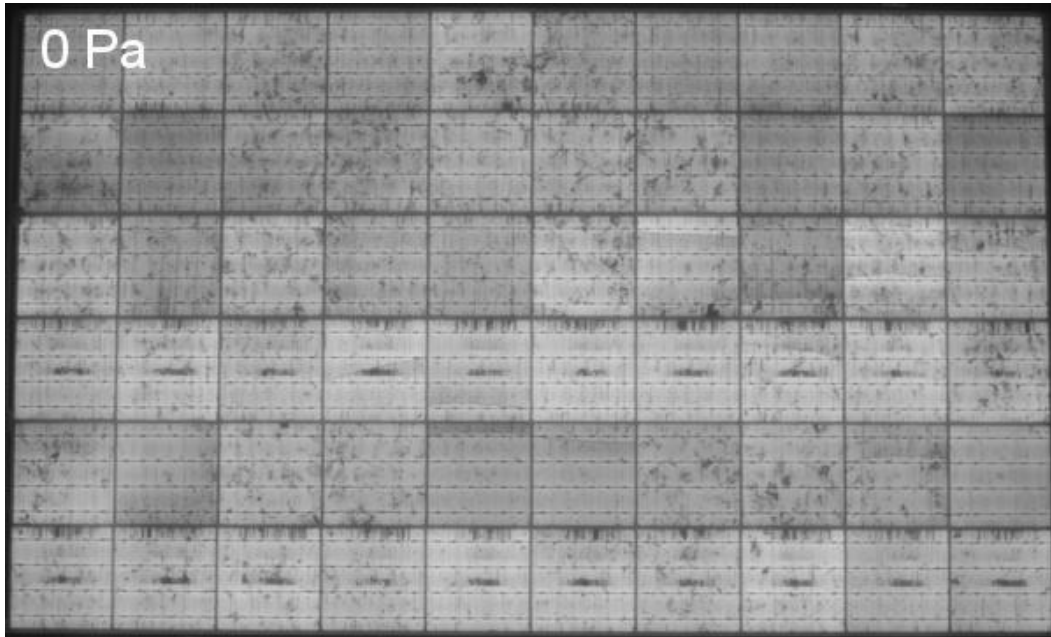


Example severe hot spot caused due to cell cracks [1]

METHODOLOGY

Mechanical Testing Equipment - LoadSpot

- Front side is unobstructed to allow for *in-situ* characterization under load
- Electroluminescence Camera and Sinton FMT solar simulator are used for characterization



 **BrightSpot Automation**



 **Sinton**
instruments

Typical Mechanical Evaluations – Front Side Loads

- A front side mechanical load puts cells into tension, which propagates micro-cracks into full cell cracks.
- These cell cracks tend to close upon removal of the mechanical load
- This results in very minimal power degradation even with a large number of fractured cells

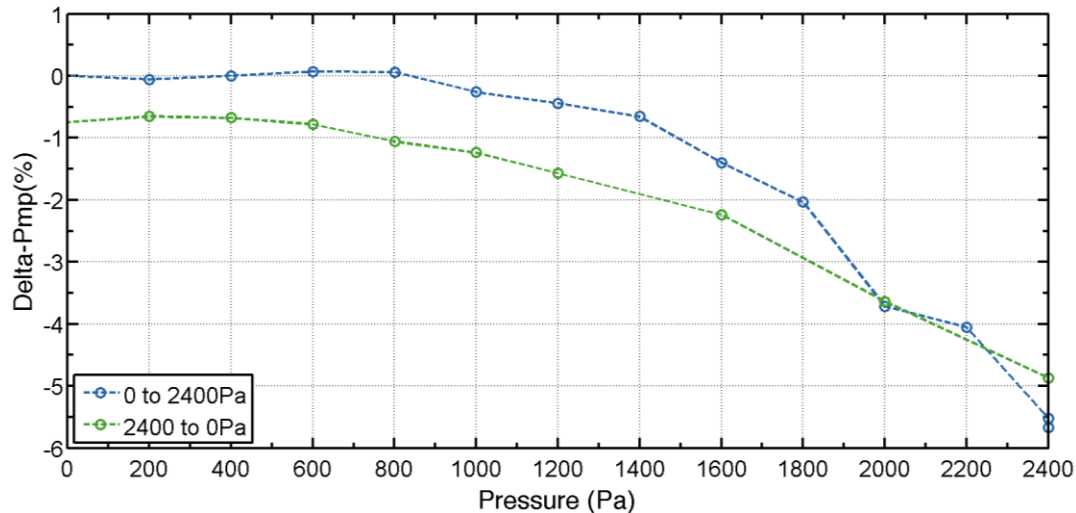
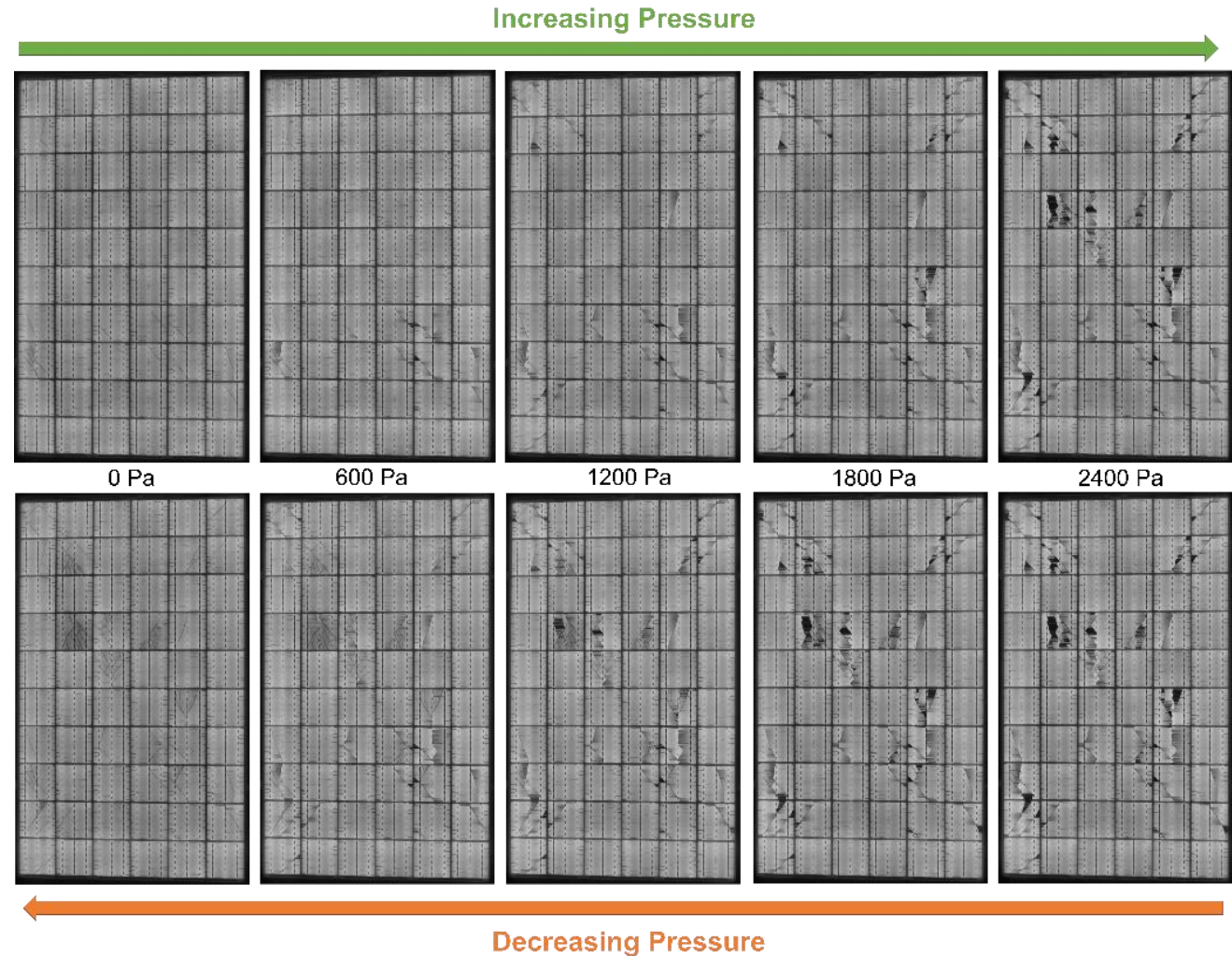
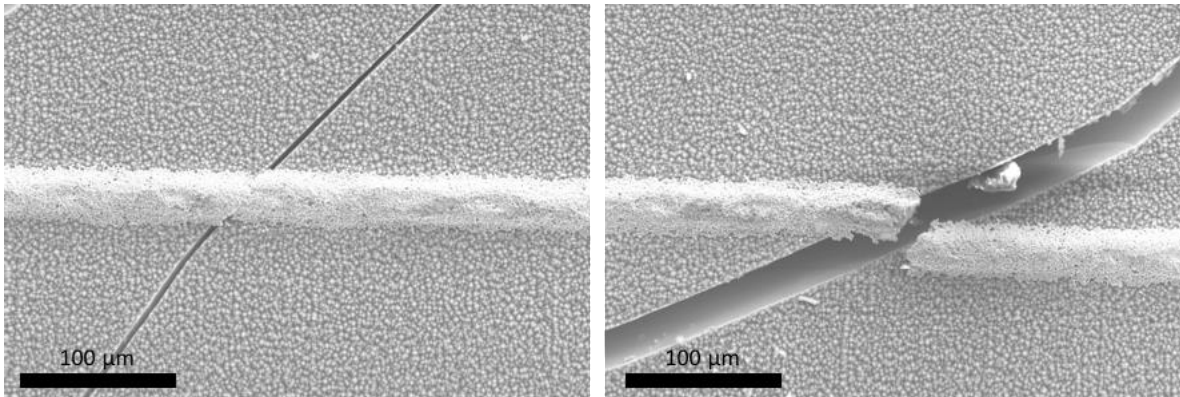


Figure: Change in maximum power as a function of applied load for both increasing (blue) and decreasing (green) pressure

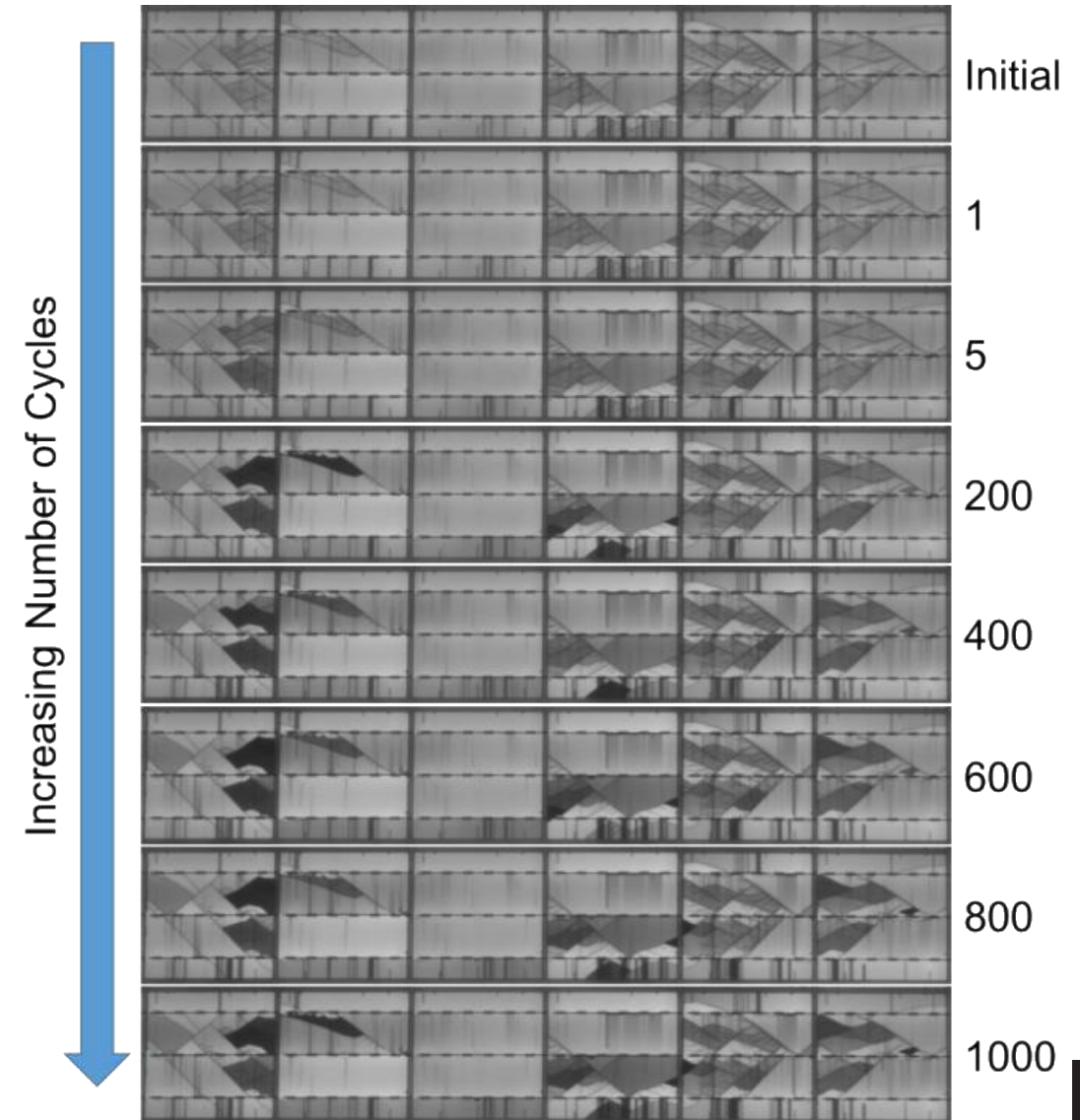


Typical Mechanical Evaluations – Cyclic Loading

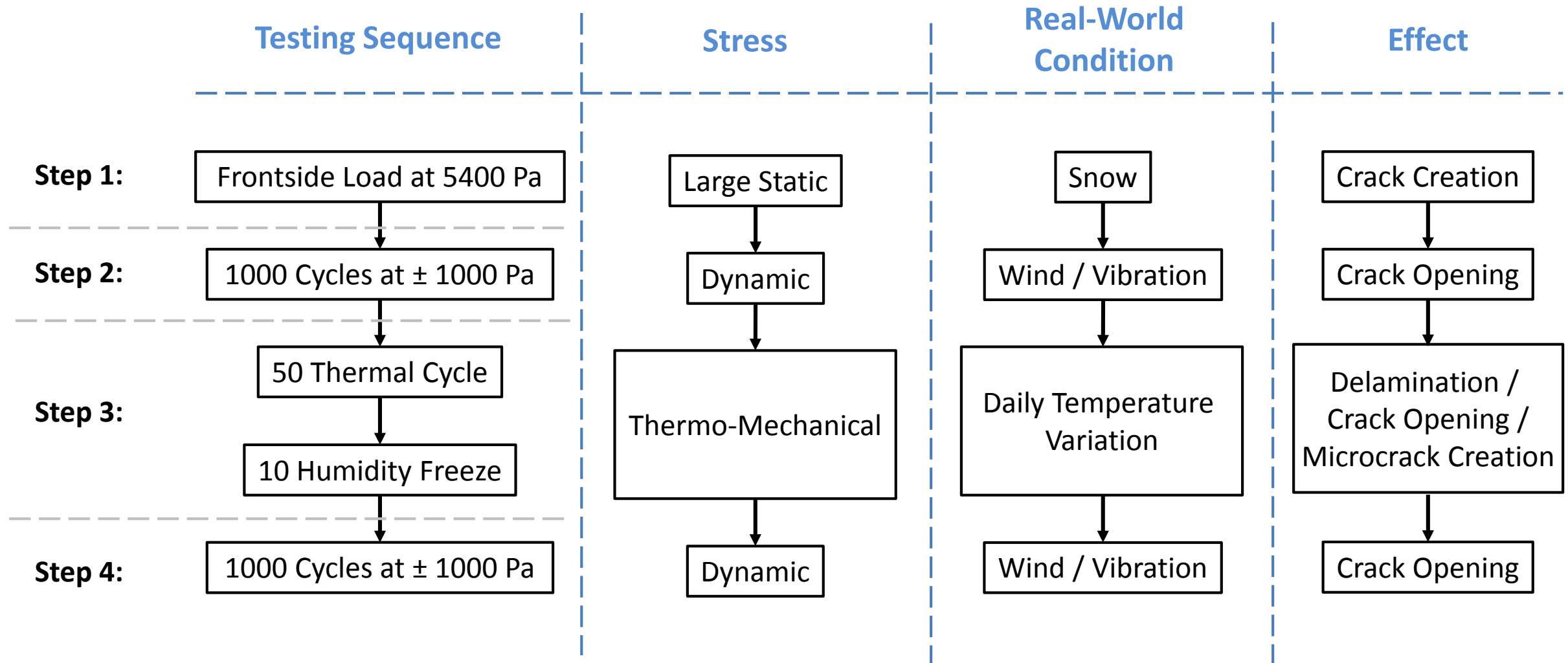
- Standard Cyclic loading sequence is 1000 cycles of $\pm 1000\text{Pa}$
- Cyclic loading assists in the transition of benign cracks into electrical isolation
- Electrical isolation has been directly related to power loss



SEM images of cell cracks that exhibit electrical conduction (left) and electrical isolation (right) of the metallization



Mechanical Evaluation Protocol



Objective: Evaluate a module design with respect to crack creation and crack opening

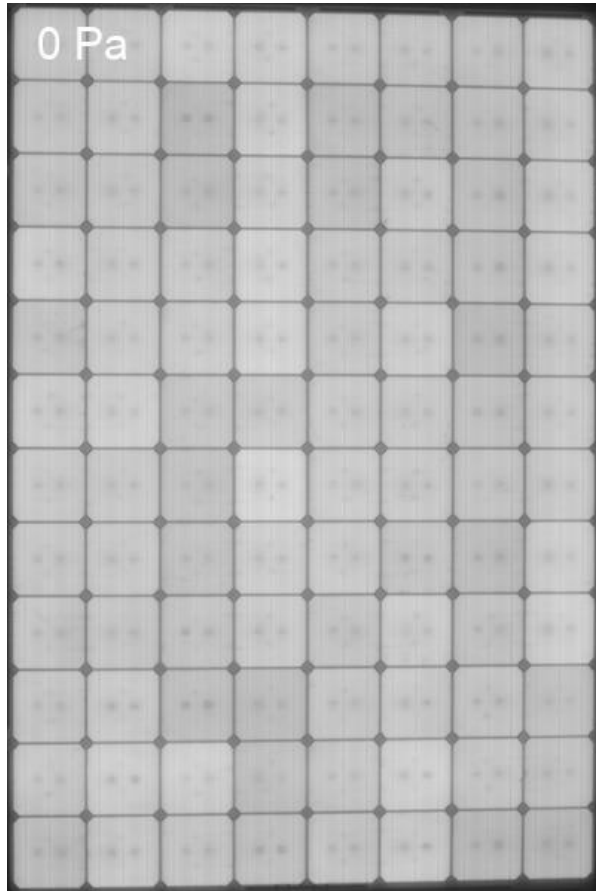
EXPERIMENTAL RESULTS

Module Technologies

Cell Technology	Interconnect Technology	Cell Size	Number of Cells
HIT	3 Busbar Low Temperature Interconnects	5 inch pseudo-square	96
Mono-PERC	4 Busbar Solder Interconnects	6 inch pseudo-square	60
Multi-PERC	4 Busbar Solder Interconnects	6 inch square	60
Mono-PERT	Wire Interconnects	6 inch pseudo-square	60

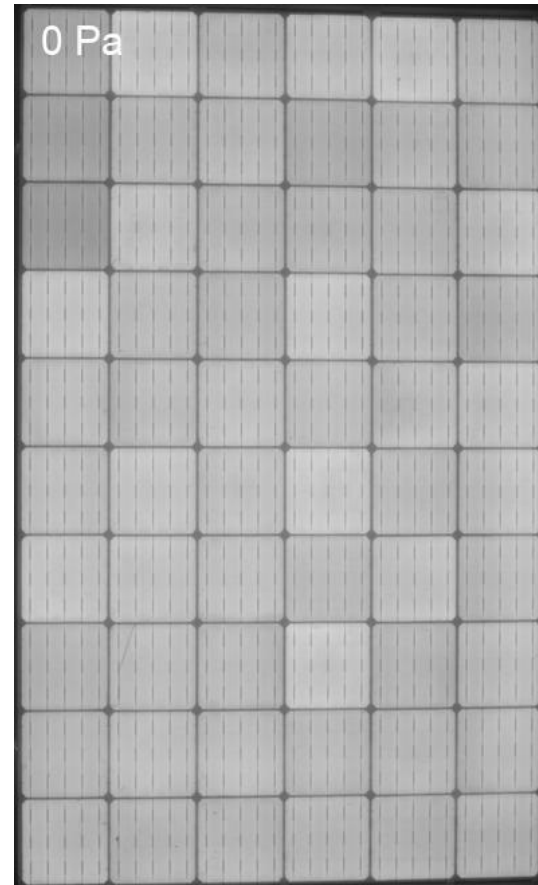
Step 1 – Static Load – Crack Creation

Frontside Load up to 5400Pa



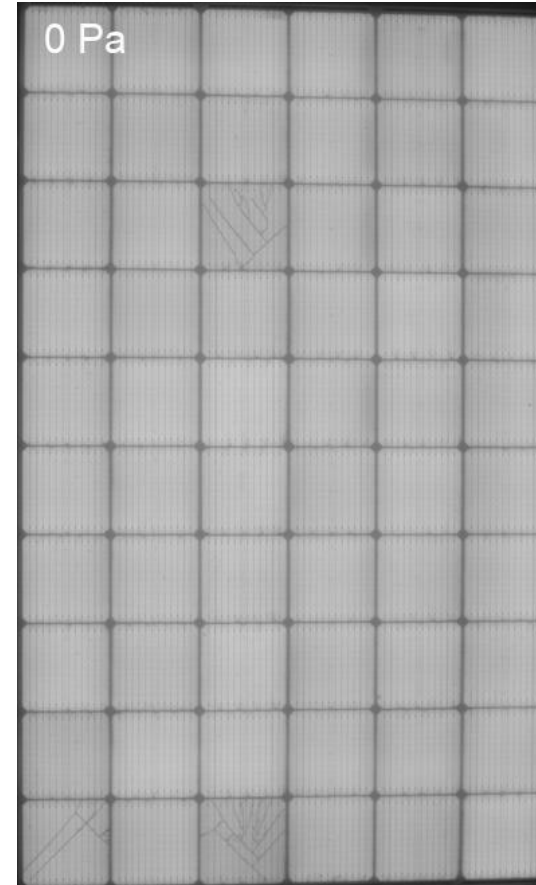
HIT

0 Cracked Cell



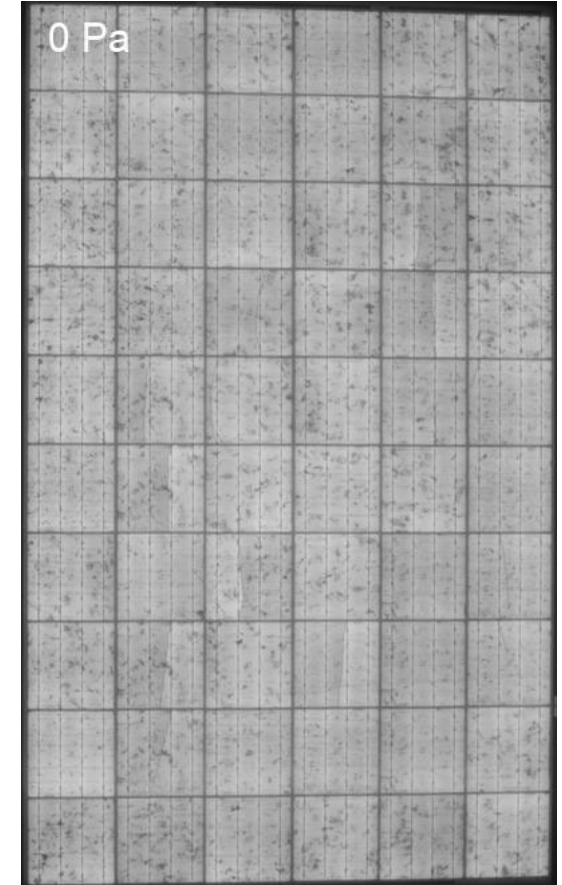
Mono-PERC

4 Cracked Cells



Mono-PERT

7 Cracked Cells



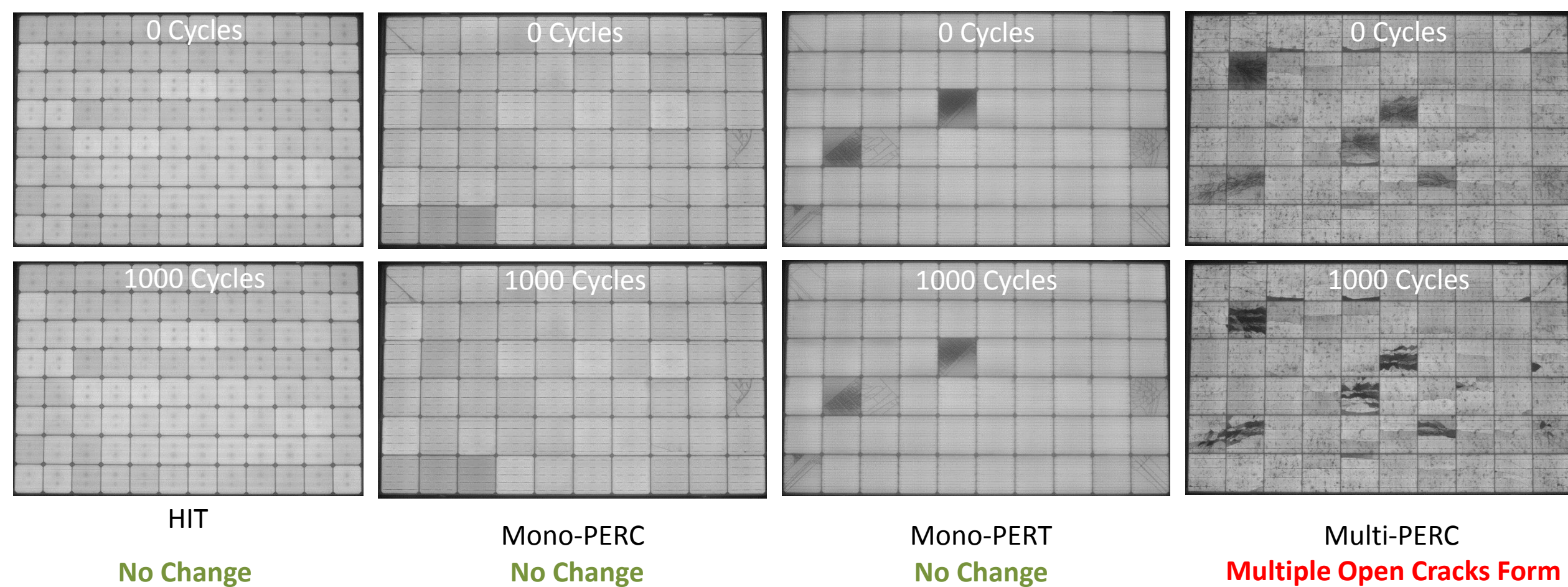
Multi-PERC

37 Cracked Cells

- There is a clear differentiation between module designs with respect to crack creation with a front-side load up to 5400 Pa

Step 2 – Cyclic Loading – Crack Opening

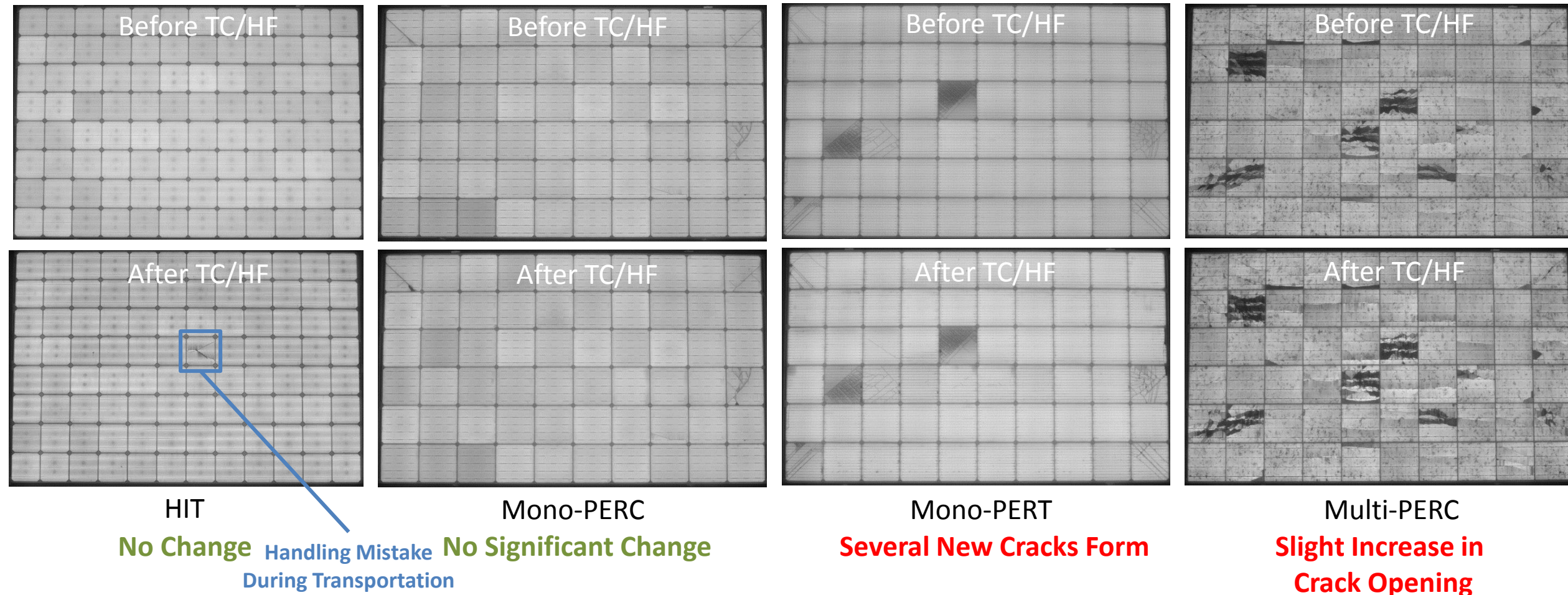
1000 Cycles at $\pm 1000\text{Pa}$



- Cyclic loading tends to open cracks on heavily damaged modules (see Multi-PERC)
- Wire interconnects appear to prevent crack opening due to redundant design (see Mono-PERT)

Step 3 – Environmental Chamber

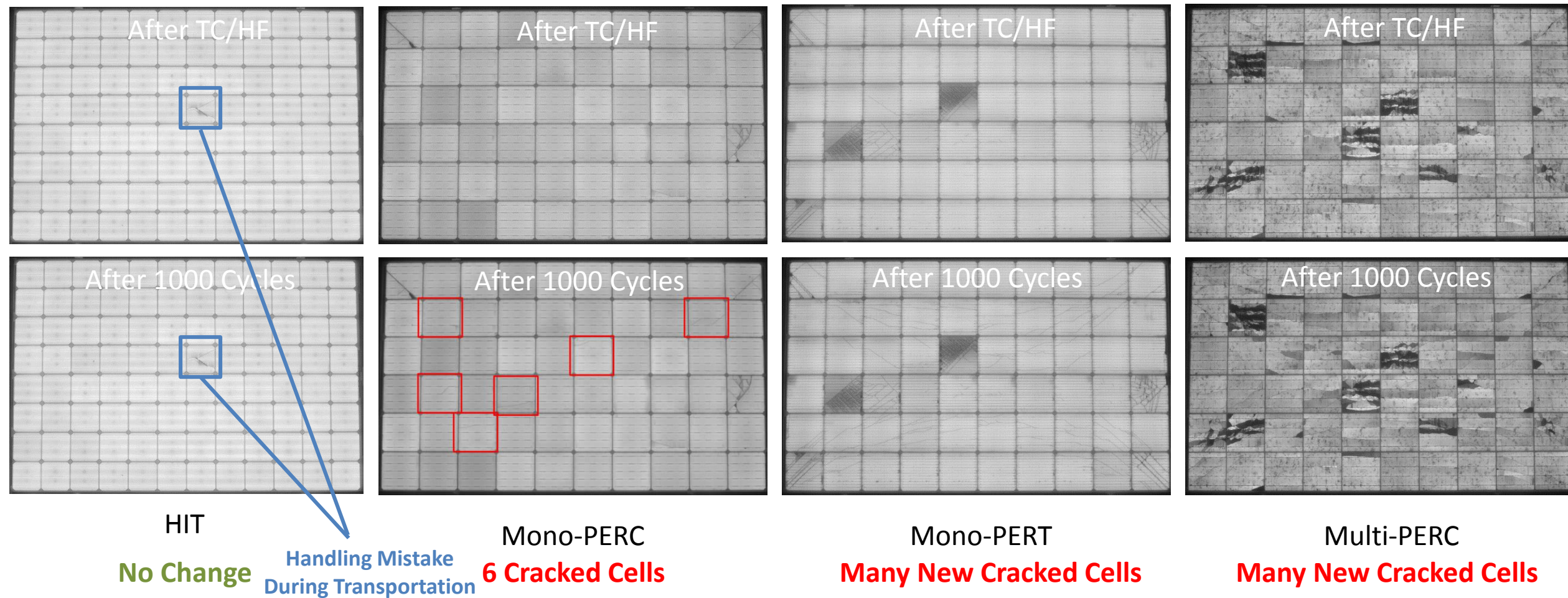
TC50 / HF10



- Very minimal change in power for all modules
- Minor change in number of cracks and dark area associated with cracks for Mono-PERT and Multi-PERC

Step 4 – Final Mechanical Stress

1000 Cycles at $\pm 1000\text{Pa}$



- Thermal Cycling has a major impact on the creation of micro-cracks^{1,2}
- Cell cracks appear to initiate near busbars and propagate with only a mild load of 1000 Pa for Mono-PERT and Multi-PERC Modules.
- The interconnect scheme and choice of encapsulant is the likely reason for superior performance of HIT Modules

[1] Seigneur, Hubert et al. "Micro-crack Formation in Silicon Solar Cells during Cold Temperatures" *In Press - IEEE JPV*

[2] Rowell, Michael et al. "The Effect of Laminate Construction and Temperature Cycling on the Fracture Strength and Performance of Encapsulated Solar Cells." *2018 IEEE WCPEC* 3927-3931.

Power Degradation

I-V data was captured to assess the impact on performance due to each exposure step.

High Power Loss (> 5%)

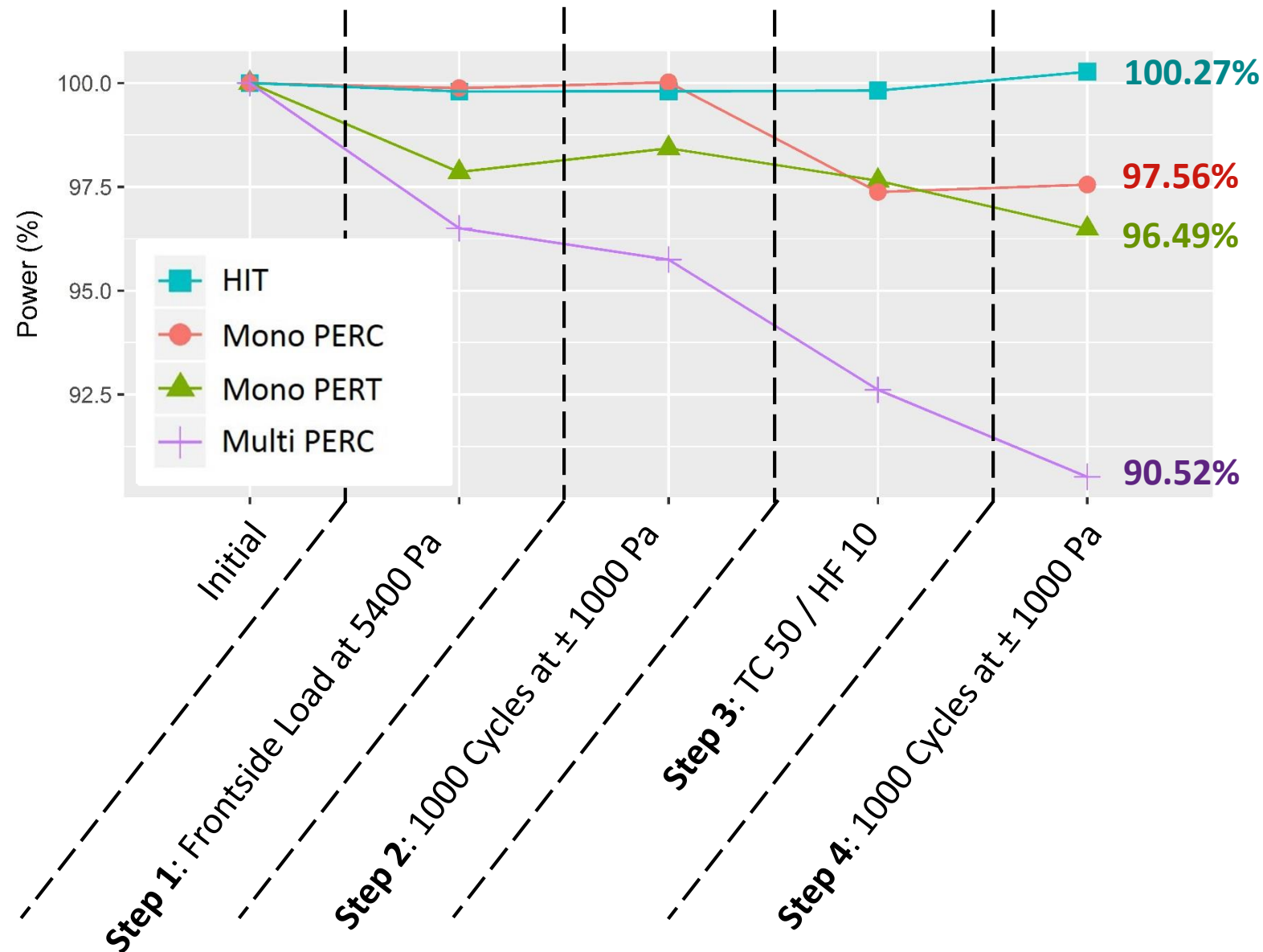
- Multi PERC

Mild Power Loss (2-5%)

- Mono PERT
- Mono PERC

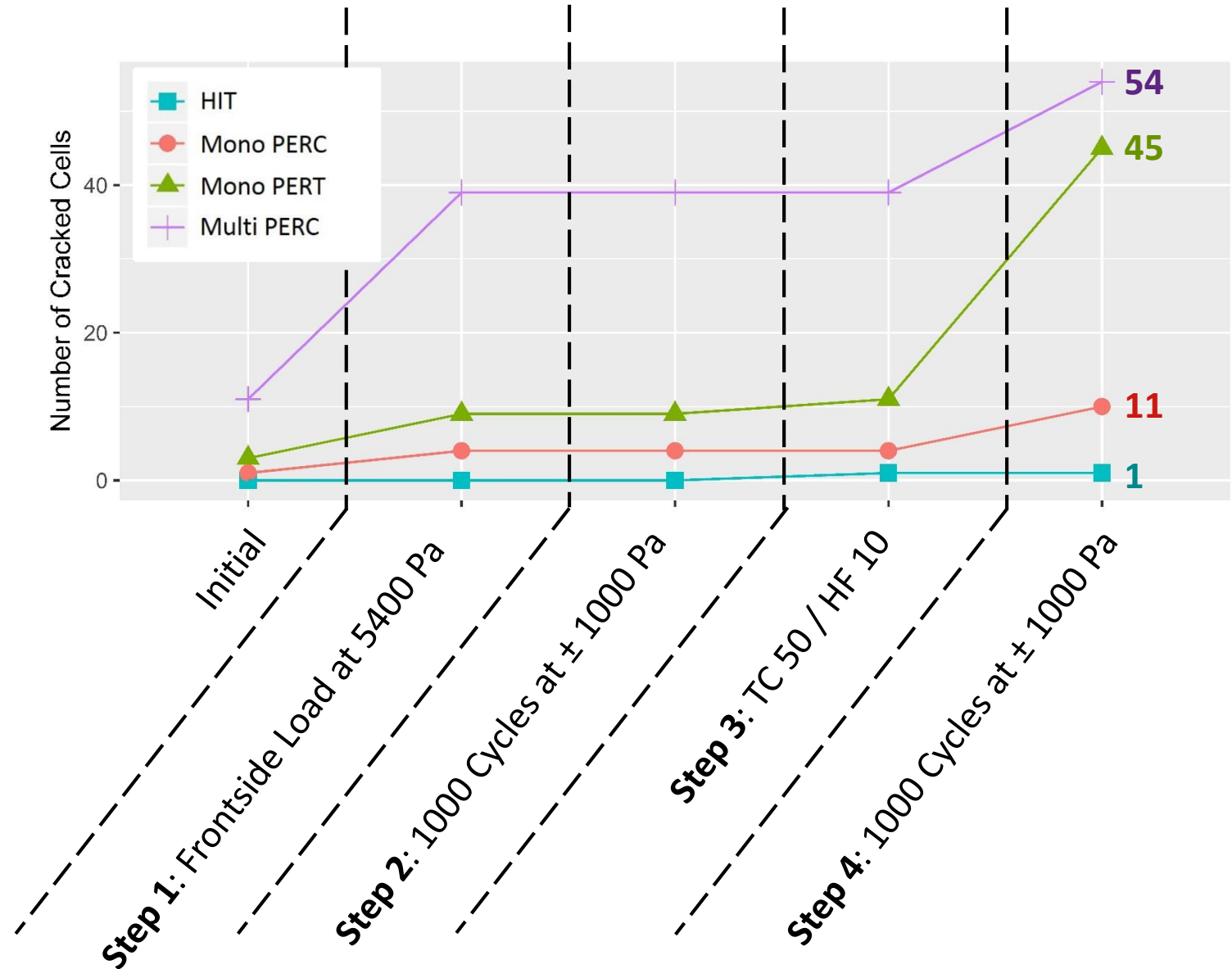
No Significant Power Loss

- HIT



Crack Creation

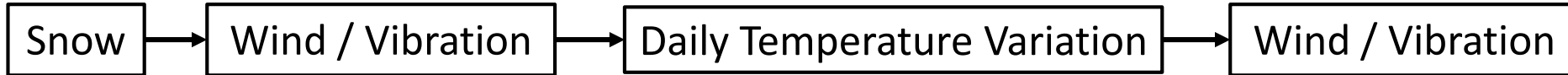
- The number of cracked cells were counted to identify which exposure steps contributed to cell cracks
- The initial frontside load of 5400Pa and the mechanical load after TC/HF contributed the most number of new cracked cells
- The HIT module only exhibited a single crack, which was the result of a handling mistake during transportation



DISCUSSION / CONCLUSION

Discussion

- A modified testing sequence was proposed to evaluate module design with respect to crack durability
 - A large front side static load is used to create cracks
 - Subsequent cyclic loading and thermal cycling is used to open cracks

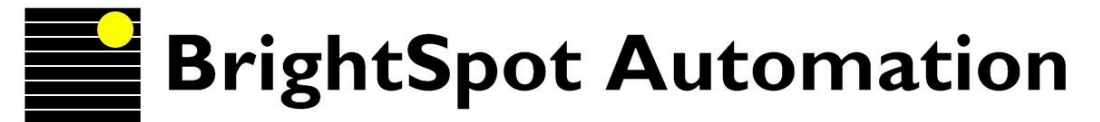


- Key Takeaways
 1. Large variation in crack durability across commercially available modules
 2. HIT modules, utilizing a symmetric cell structure and low temperature interconnect process, exhibit high durability with respect to crack generation
 3. Mechanical loading after thermal cycling causes a significant number of new cracks for modules with solder interconnects



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Panasonic



THANK YOU

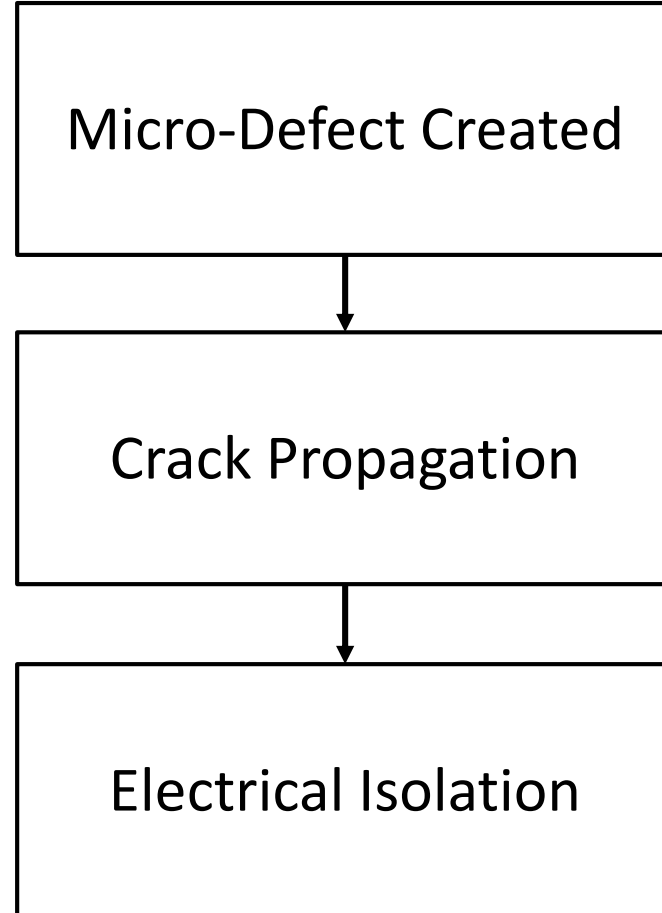
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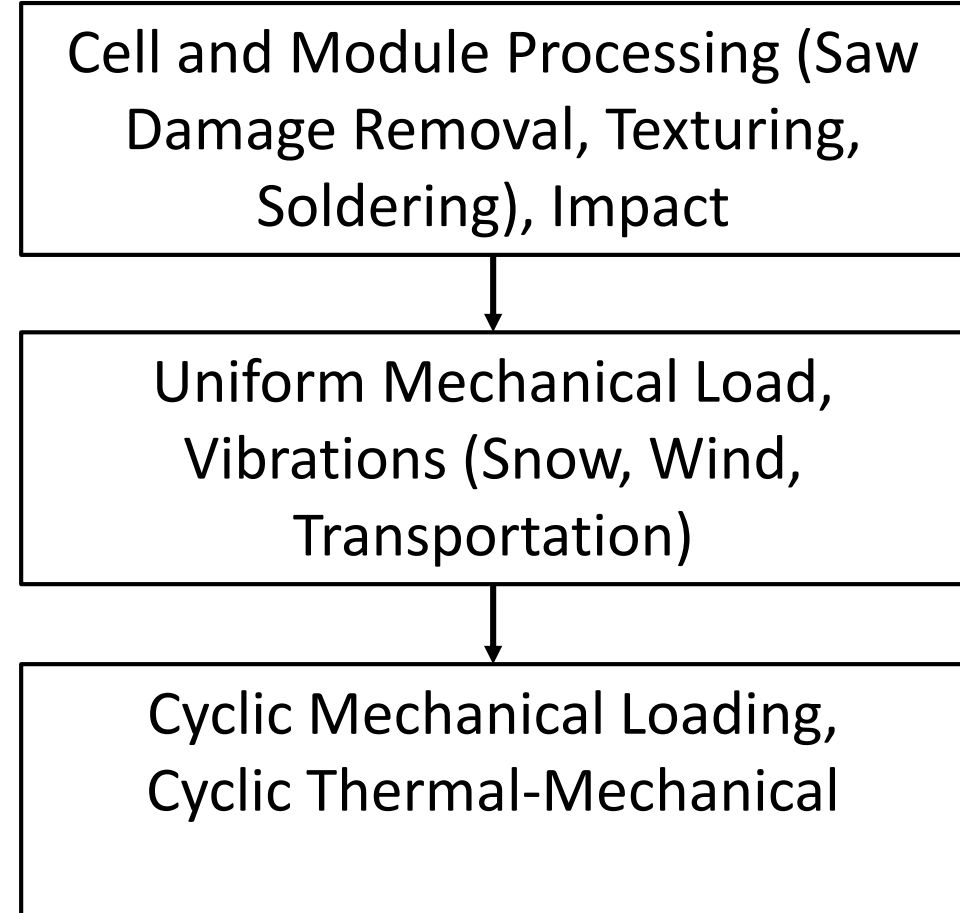
EXTRA SLIDES

Origin of Cell Cracks

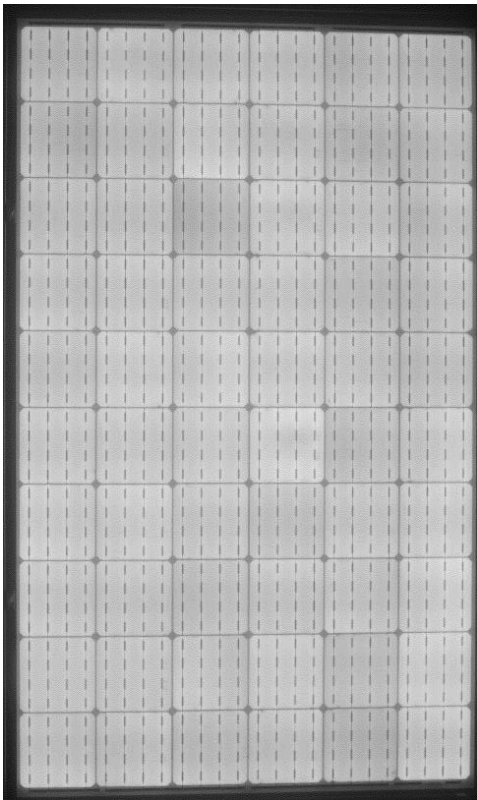
Degradation Pathway



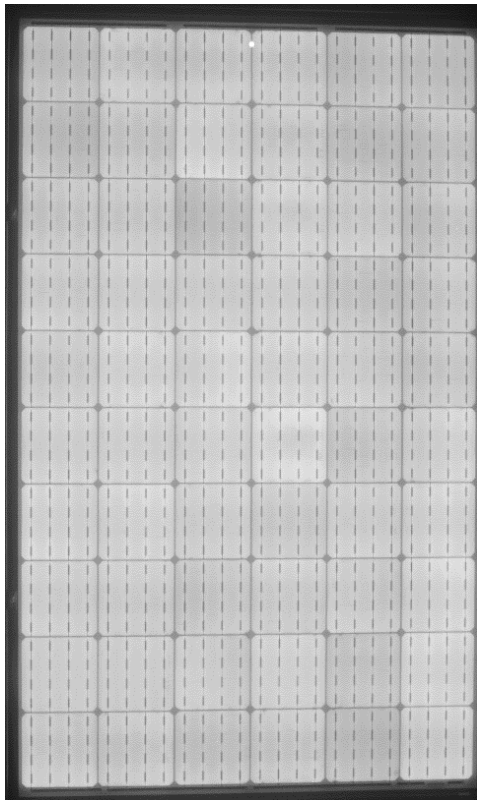
Physical Causes



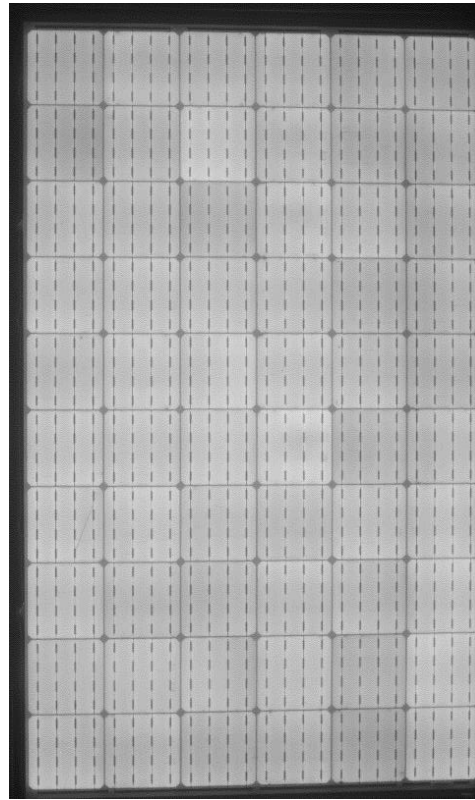
Impact of Single Thermal Cycle



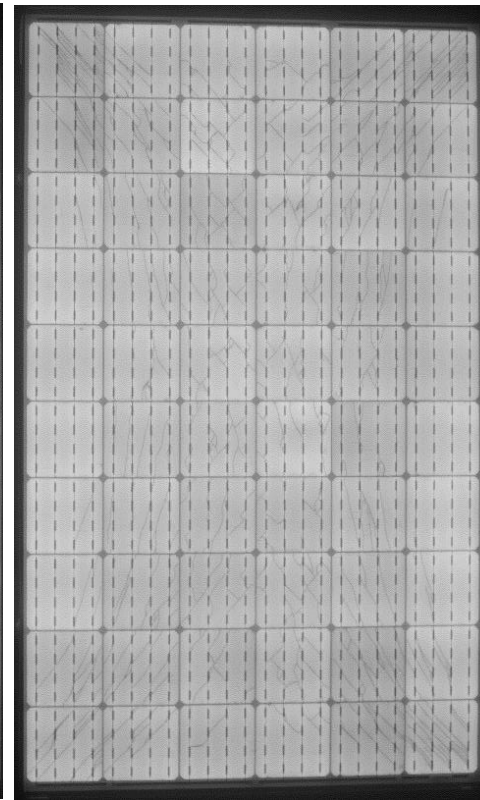
Initial



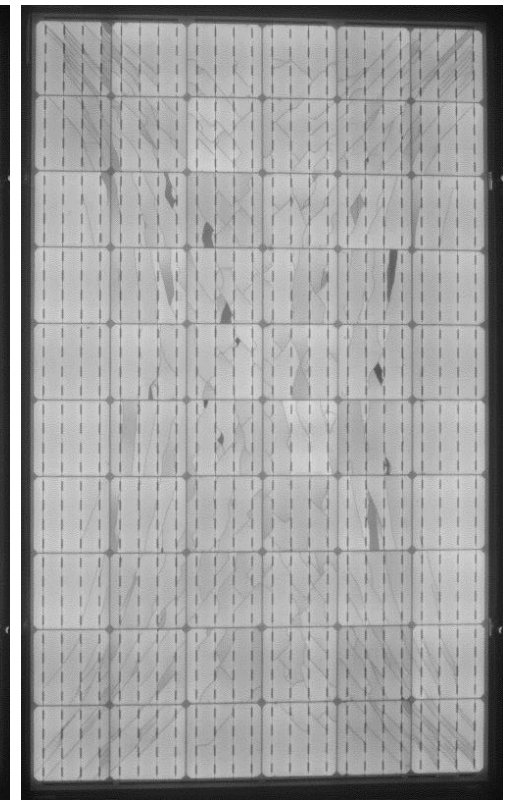
3600Pa Load



1 Thermal Cycle

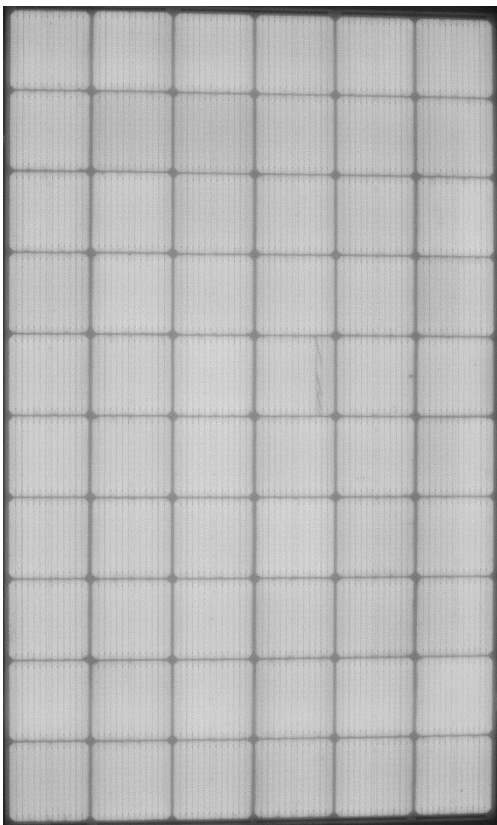


3600Pa Load

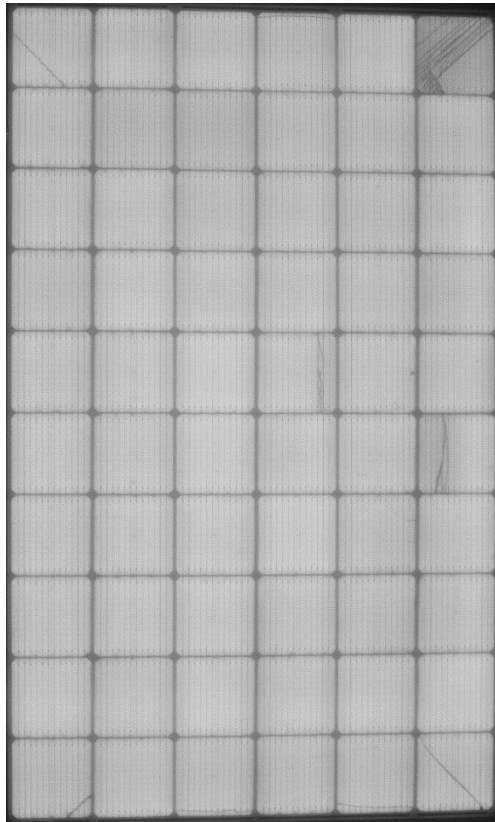


1000 Cycles
at ± 1000 Pa

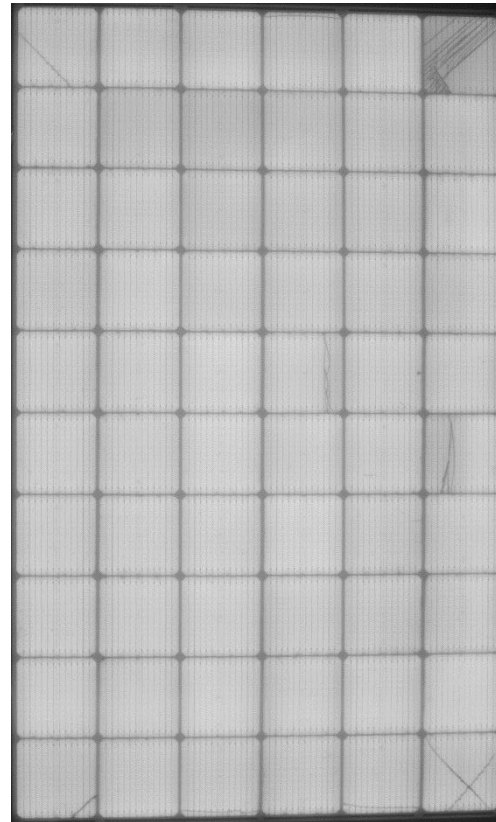
Cold Exposure on Wire Interconnect Module



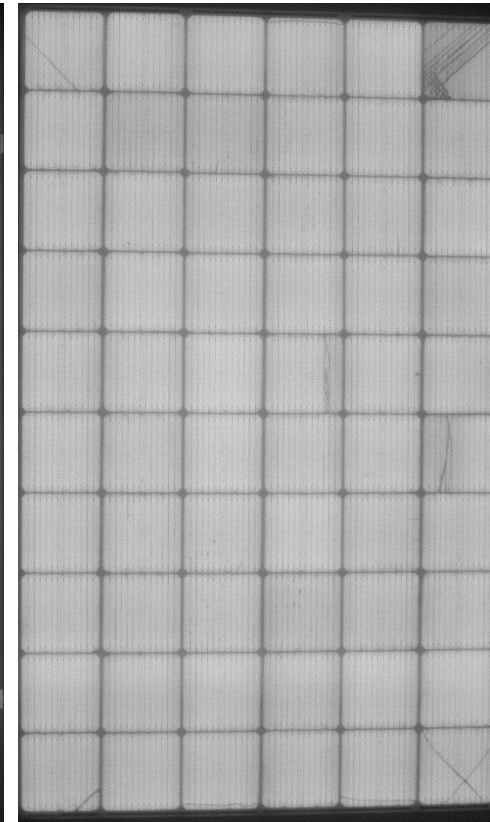
Initial



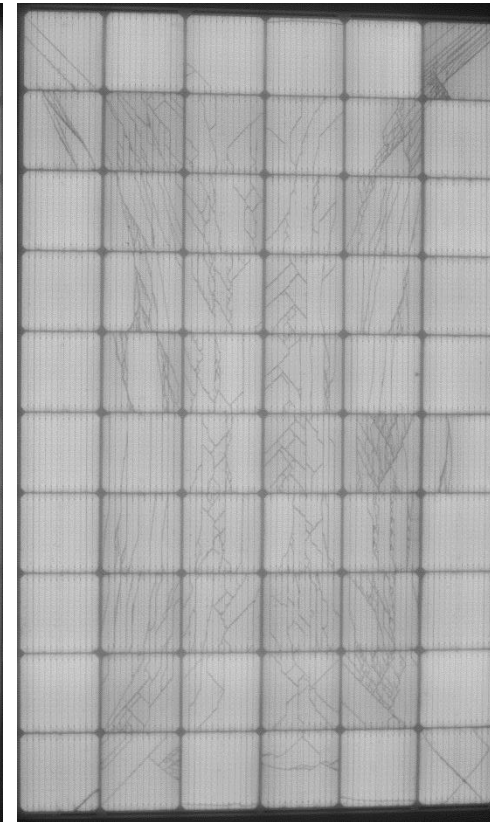
5400Pa Load



1000 Cycles at ± 1000 Pa



1 COLD Cycle



2400Pa Load